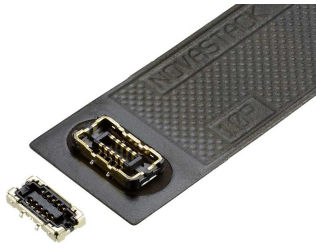


NOVASTACK® 35-HDN

Ideal for 5G mmWave antenna module and devices, fully-shielded and narrow design, Power supply is available with Corson Alloy contact, 0.35 mm pitch, 0.7 mm height



- ✓ Ideal for high frequency applications (5G mmWave, USB4 / Thunderbolt 3, etc.)
- ✓ ZenShield® fully-shielded design, decreases EMI issue caused by 5G applications
- ✓ Narrow depth and low height, fully-shielded board-to-board connector

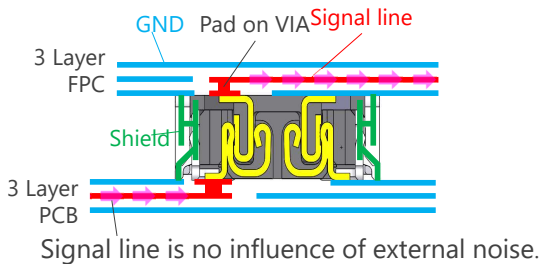
Pin counts:

Range	Up to 60
Available	10, 20, 30

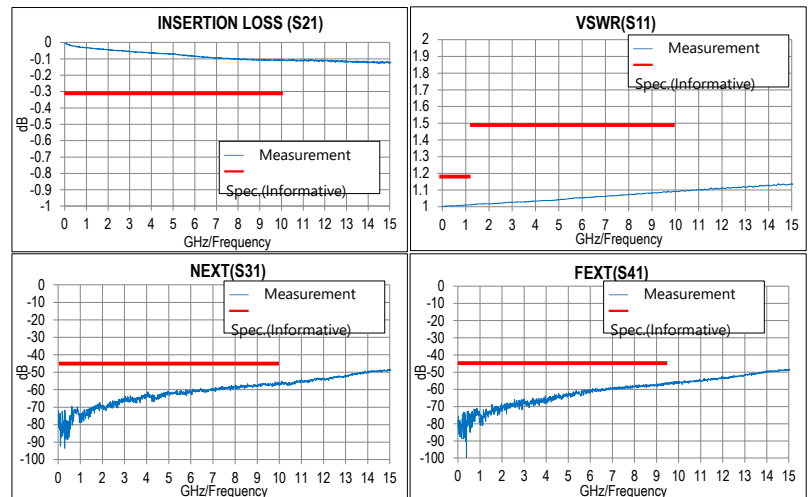
*Please inquire for pin counts not listed or outside of the pin count range.

Mating type		Board-to-board (FPC)
Board pitch (mm)		0.35
Mated size (mm)	Height	0.7 +/- 0.05
	Width (mm)	4.15 (10P) 5.90 (20P) 7.90 (30P)
	Depth	2.15 mm
Current Rating	Signal Pin	1.0A / Pin (Max. 10P) (12 pin and over : 12.0 A AC/DC (Total))
Performance (Reference only)		USB® 3.1 (10 Gbps) Thunderbolt 3 (20 Gbps) mmWave for 5G (15 GHz)

Ideal for high frequency applications (5G mmWave, USB4 / Thunderbolt 3, etc.)

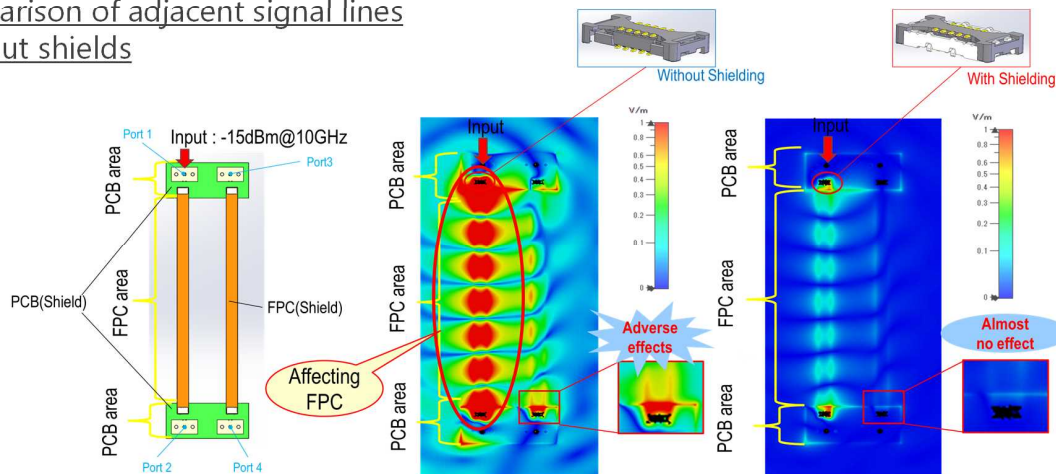


◆ Pin assignment



ZenShield® fully-shielded design, decreases EMI issue caused by 5G applications

E-Field comparison of adjacent signal lines with or without shields



Narrow depth and low height, fully-shielded board-to-board connector

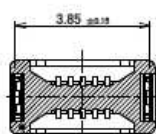
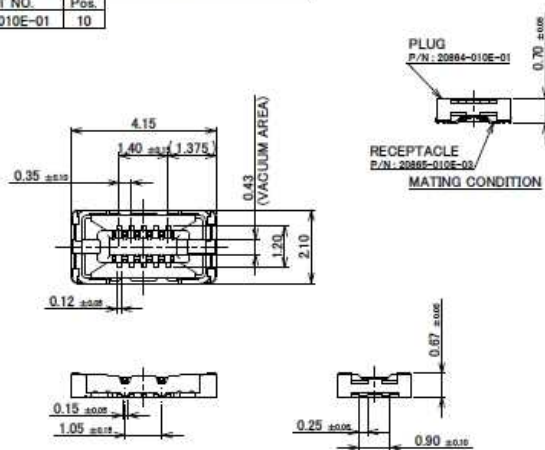


NOVASTACK® 35-HDN

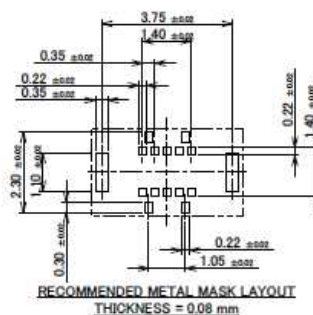
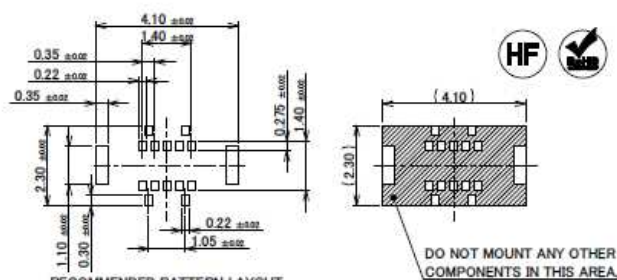
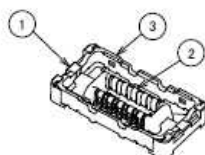
Component Parts Detail

Plug Assembly :

Recommended P/N		20864-010E-01
PART NO.	Pos.	
20864-010E-01	10	



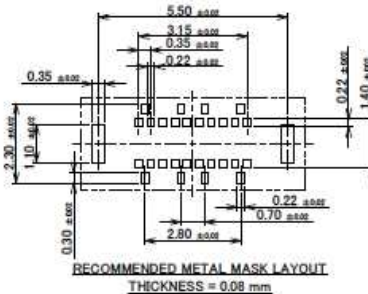
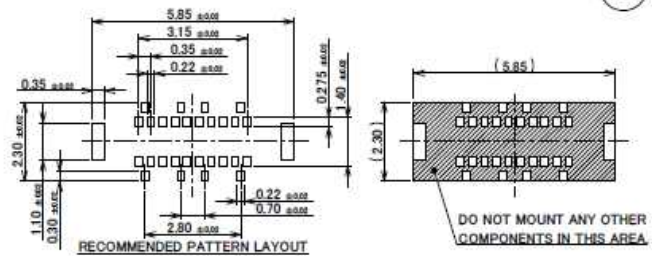
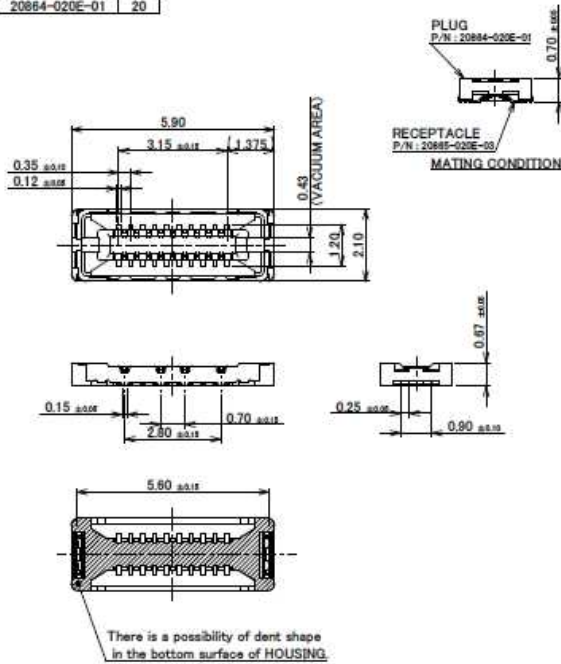
There is a possibility of dent shape
in the bottom surface of HOUSING.



3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRPTION	MATERIAL	FINISH, REMARKS

Plug Assembly :

Recommended P/N		20864-020E-01
PART NO.	Pos.	
20864-020E-01	20	

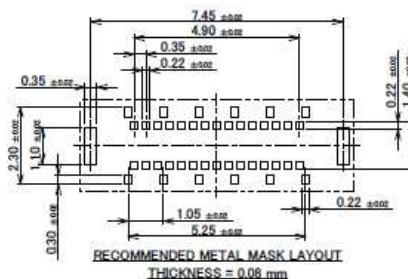
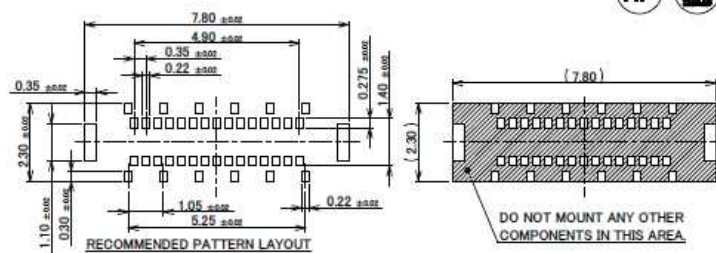
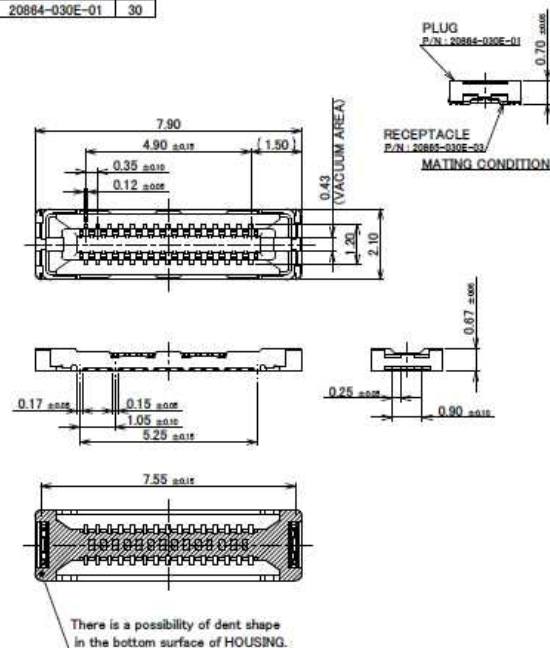


3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.8

Plug Assembly :

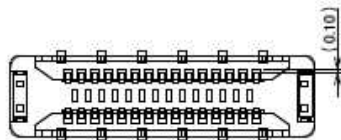
Recommended P/N		20864-030E-01
PART NO.	Pos.	
20864-030E-01	30	



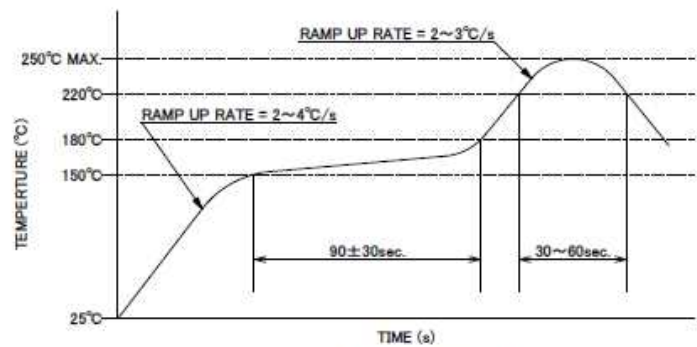
3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μ m MIN. OVER Ni 1.27 μ m MIN. SOLDERING PART Au 0.01 μ m MIN. OVER Ni 1.27 μ m MIN.
1	HOUSING	LCP	UL94V-0, BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.8

Plug Assembly :



CONNECTOR ON RECOMMENDED FOOTPRINT PATTERN



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.8

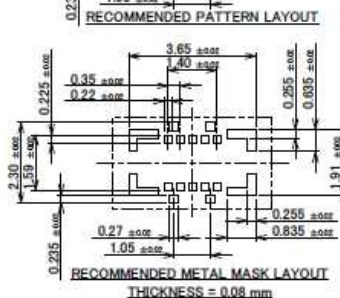
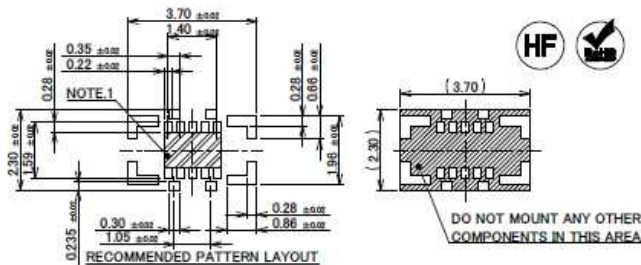
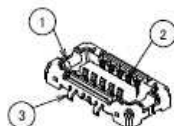
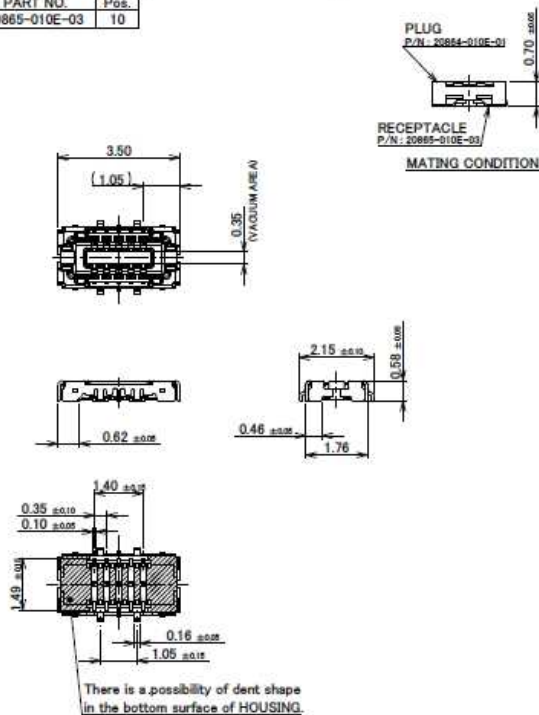
Plug Assembly :

ITEMS	SPECIFICATION
RATING VOLTAGE	60V AC(r.m.s) / DC (PER A CONTACT)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERARING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENDING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : \triangle 140mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : \triangle 120mohm MAX.
INSULATION RESISTAMCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18022
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.8

Receptacle Assembly :

Recommended P/N		20865-010E-03
PART NO.	Pos.	
20865-010E-03	10	



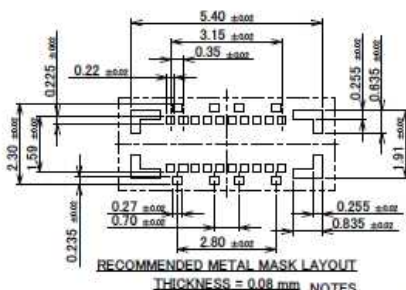
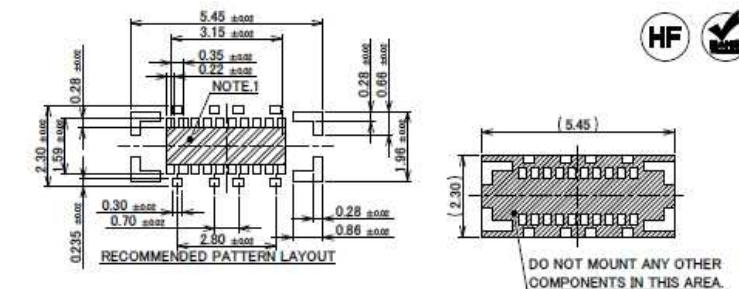
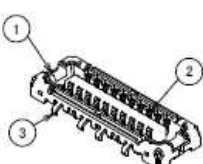
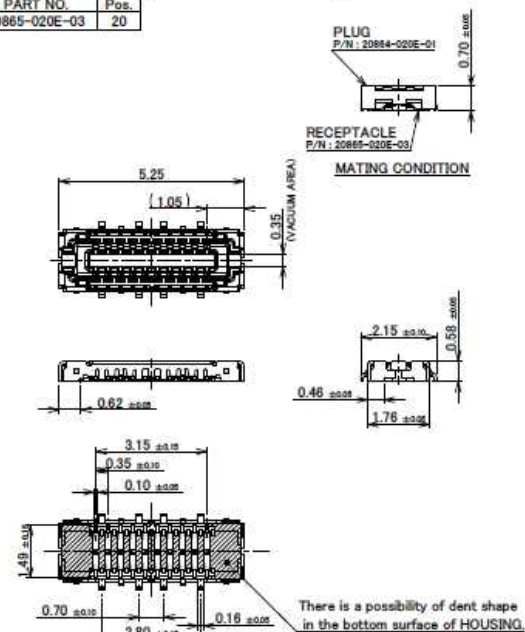
NOTES
1. FOOT PRINT PATTERN PROHIBITION AREA :
SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

3	SHELL	COPPER ALLOY	SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.8

Receptacle Assembly :

Recommended P/N		20865-020E-03
PART NO.	Pos.	
20865-020E-03	20	



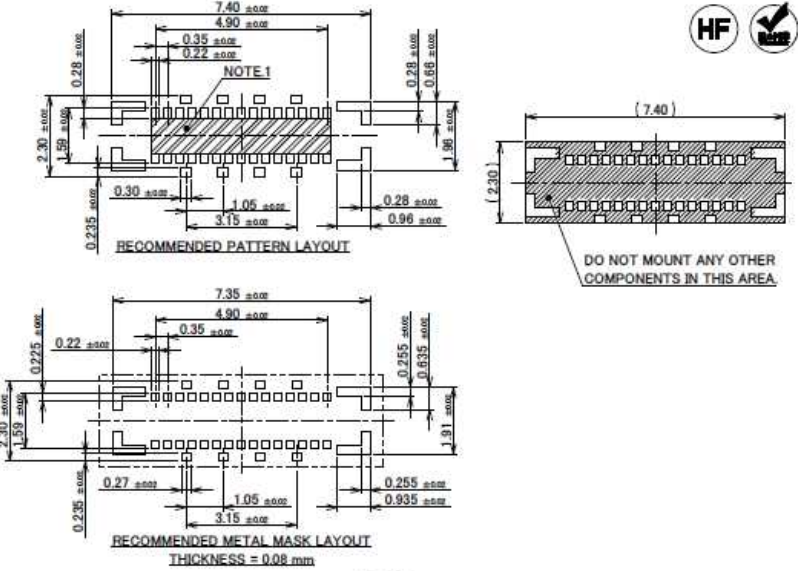
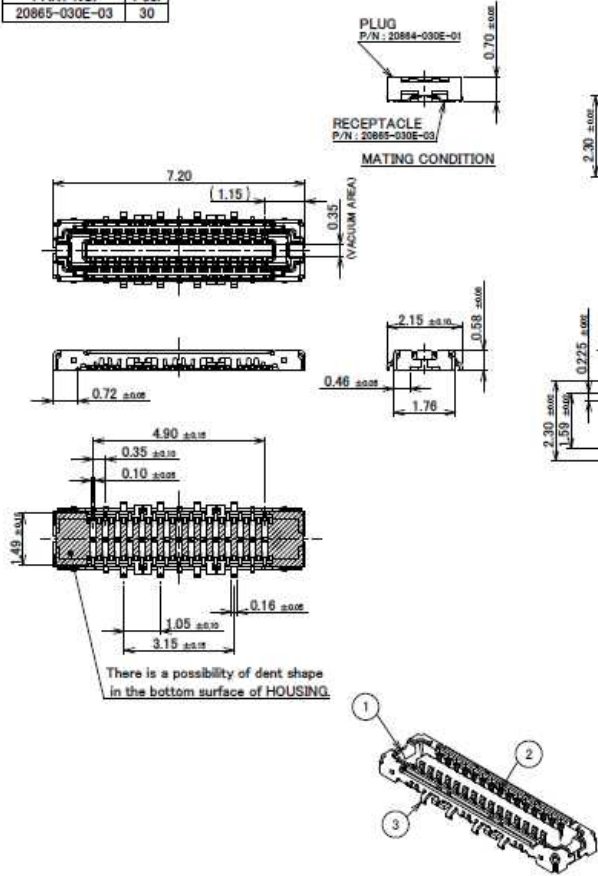
NOTES
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SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
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2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.8

Receptacle Assembly :

Recommended P/N	
20865-030E-03	
PART NO.	Pos.
20865-030E-03	30

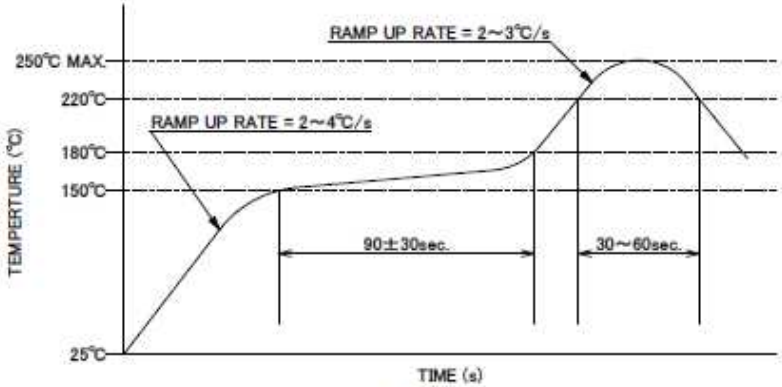
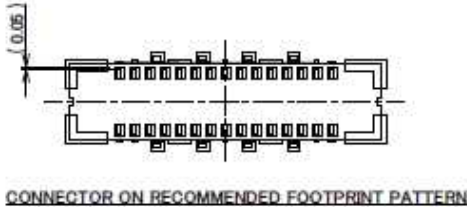


NOTES.
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SOLDER RESIST MUST BE APPLIED TO THIS HATCHED AREA
IF SURFACE TRACES ARE ROUNDED.

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2	CONTACT	COPPER ALLOY	CONTACT PART Au 0.05 μm MIN. OVER Ni 1.27 μm MIN. SOLDERING PART Au 0.01 μm MIN. OVER Ni 1.27 μm MIN.
1	HOUSING	LCP	UL94V-0 BLACK
NO.	DISCRIPTION	MATERIAL	FINISH, REMARKS

Rev.8

Receptacle Assembly :



REFLOW TEMPERATURE PROFILE
SENJU METAL INDUSTRY CO., LTD. : M705-SHF(Sn96.5 Ag3.0 Cu0.5)

Rev.8

Receptacle Assembly :

ITEMS	SPECIFICATION
RATING VOLTAGE	60V AC(r.m.s) / DC (PER A CONTACT)
RATING AMPERAGE (FOR SIGNAL CONTACT)	10P:1.0 A MAX. AC/DC x PIN COUNTS = 10.0 A (TOTAL) 12P AND OVER : 12.0 A AC/DC (TOTAL)
OPERATING TEMPERATURE	233~358K(-40°C~85°C)
OPERATING HUMIDITY	85% MAX.(NON-CONDENDING)
CONTACT RESISTANCE (FOR SIGNAL CONTACT)	INITIAL : 40mohm MAX. / AFTER TEST : Δ 40mohm MAX.
CONTACT RESISTANCE (FOR GROUND)	INITIAL : 20mohm MAX. / AFTER TEST : Δ 20mohm MAX.
INSULATION RESISTANCE	INITIAL : 1,000Mohm MIN. / AFTER TEST : 500Mohm MIN.
DIELECTRIC WITHSTANDING VOLTAGE	AC250V 1min
DURABILITY	10 CYCLES
MATING FORCE (INITIAL / AFTER TEST)	INITIAL 2.0N/Pin MAX.
UNMATING FORCE (INITIAL / AFTER TEST)	10 CYCLES 0.15N/Pin MIN.
COPLANARITY	0.08 MAX.
PRODUCT SPECIFICATION	PRS-2607
TEST REPORT	TR-19055
PACKING STANDARD	PST-18023
INSTRUCTION MANUAL	HIM-18019
APPEARANCE CRITERIA No.	QLS-A***

Rev.8



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Contact your sales representative for more detailed information. [i-pex.com]